

Material Composition Specification

SOD-323F Case



Device average mass 4.1 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	Silicon	1.41%	0.058	Si	7440-21-3	1.34%	0.05491	950000
	Gold			Au	7440-57-5	0.062%	0.00254	44000
	Antimony			Sb	7440-36-0	0.001%	0.00006	1000
	Silicon Nitride			Si3N4	12033-89-5	0.006%	0.00023	4000
	Aluminum			Al	7429-90-5	0.001%	0.00006	1000
bond wire	gold	0.24%	0.01	Au	7440-57-5	0.24%	0.01	2,041
leadframe	Alloy 42	0.37%	0.015	Ni	7440-02-0	0.15%	0.0063	420000
				Fe	7439-89-6	0.21%	0.0087	580000
encapsulation*	EMC GREEN	97.90%	4.014	silica	60676-86-0	78.02%	3.199	797000
				epoxy resin	29690-82-2	9.79%	0.40144	100000
				phenol resin	9003-35-4	9.79%	0.40144	100000
				carbon black	1333-86-4	0.29%	0.0120	3000
plating**	matte tin	0.068%	0.00279	Sn	7440-31-5	0.068%	0.00279	>999000
				Pb	7439-92-1	0%	.0000002	<1000

*EMC GREEN molding compound is Halogen-Free.
 **For Lead Free plating, add suffix "PB FREE" to part number.

Disclaimer
 The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.